

TABLE 1

TIN (IMMERSION)	Cu	25-50µm [1000-2000µin]
	Sn	0.9-1.5µm [35-60µin]

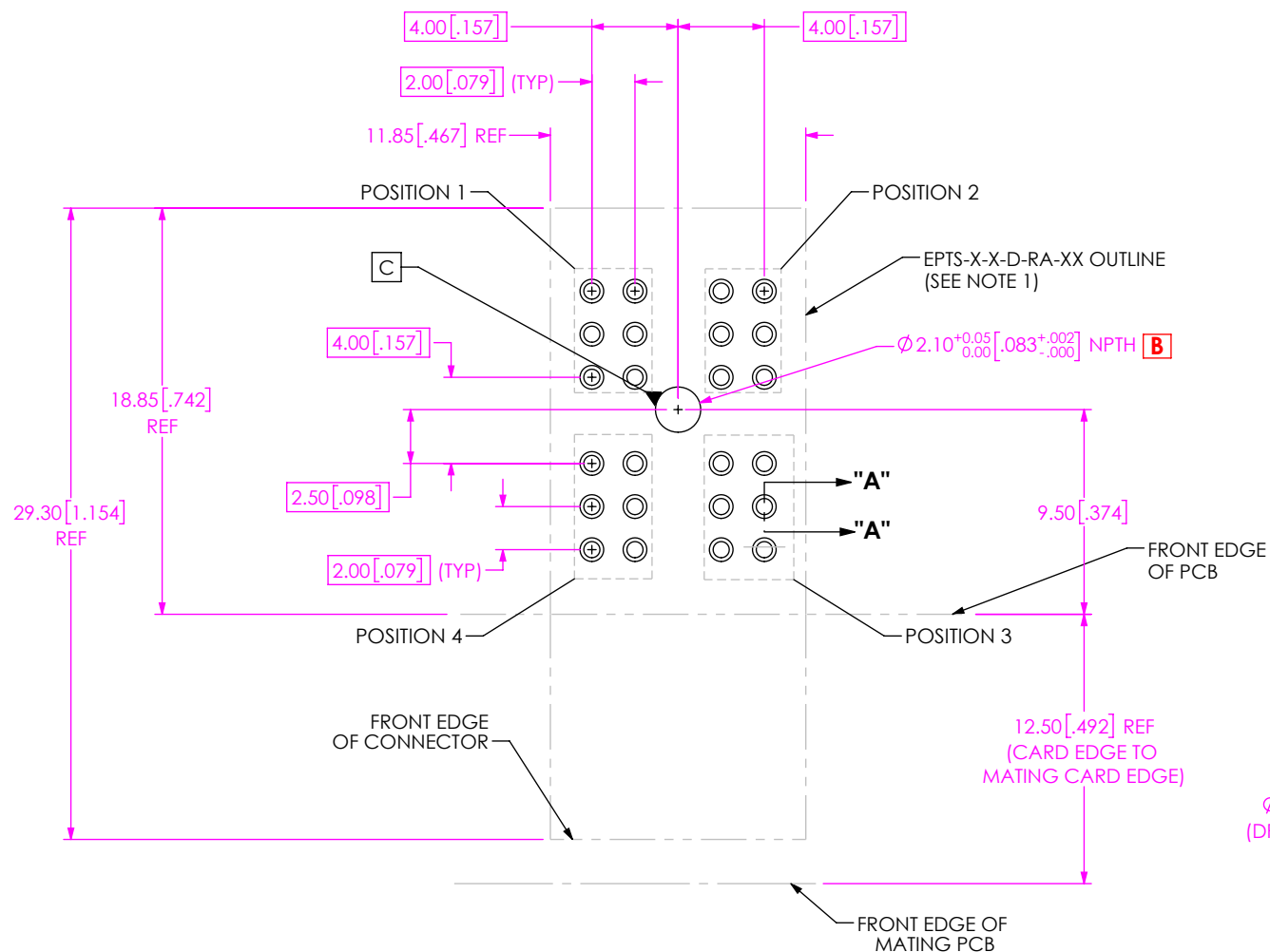
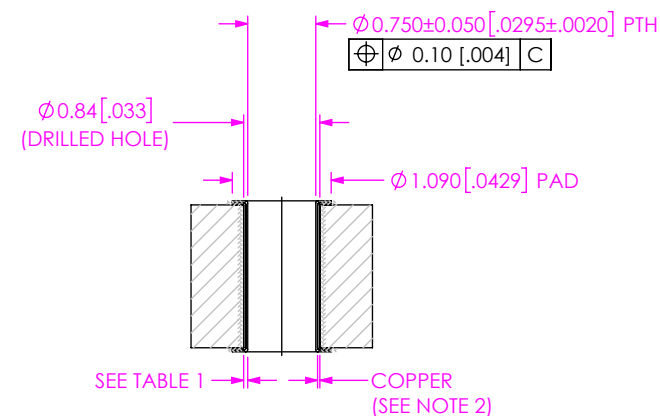


FIG 1
(SUGGESTED -2 POSITION PCB LAYOUT)
(COMPONENT SIDE SHOWN)
ALL DIMENSIONS ARE SYMMETRIC ABOUT THE CENTERLINE.



SECTION "A"-"A"

NOTES:

1. CONNECTOR ENVELOPE DIMENSIONS. OTHER COMPONENTS PLACED ON PCB SHALL AVOID THIS ZONE.
2. COPPER PLATING THICKNESS MAY NOT VARY BY MORE THAN 0.02[.001] WITHIN ANY VIA.
3. CONTACT SAMTEC FOR CONNECTOR PRESS FIT INSTRUCTIONS AND REQUIRED FIXTURES.

PROPRIETARY NOTE
THIS DOCUMENT CONTAINS CONFIDENTIAL AND PROPRIETARY INFORMATION AND ALL DESIGN, MANUFACTURING, REPRODUCTION, USE, PATENT RIGHTS AND SALES RIGHTS ARE EXPRESSLY RESERVED BY SAMTEC, INC. THIS DOCUMENT SHALL NOT BE DISCLOSED, IN WHOLE OR PART, TO ANY UNAUTHORIZED PERSON OR ENTITY NOR REPRODUCED, TRANSFERRED OR INCORPORATED IN ANY OTHER PROJECT IN ANY MANNER WITHOUT THE EXPRESS WRITTEN CONSENT OF SAMTEC, INC.

samtec

520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail info@SAMTEC.com code 55322